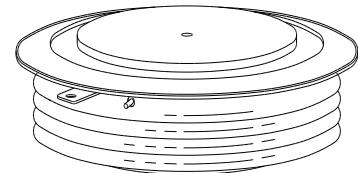


## HIGH POWER THYRISTOR FOR PHASE CONTROL APPLICATIONS

### Features:

- . All Diffused Structure
- . Interdigitated Amplifying Gate Configuration
- . Blocking capability up to 2100 volts
- . Guaranteed Maximum Turn-Off Time
- . High dV/dt Capability
- . Pressure Assembled Device



## ELECTRICAL CHARACTERISTICS AND RATINGS

### Blocking - Off State

Device Type	V <sub>RRM</sub> (1)	V <sub>DRM</sub> (1)	V <sub>RSM</sub> (1)
R600CH21	2100	2100	2200

V<sub>RRM</sub> = Repetitive peak reverse voltage

V<sub>DRM</sub> = Repetitive peak off state voltage

V<sub>RSM</sub> = Non repetitive peak reverse voltage (2)

Repetitive peak reverse leakage and off state leakage	I <sub>RRM</sub> / I <sub>DRM</sub>	200 mA (3)
Critical rate of voltage rise	dV/dt (4)	500 V/μsec

### Notes:

All ratings are specified for T<sub>j</sub>=25 °C unless otherwise stated.

(1) All voltage ratings are specified for an applied 50Hz/60Hz sinusoidal waveform over the temperature range -40 to +125 °C.

(2) 10 msec. max. pulse width

(3) Maximum value for T<sub>j</sub> = 125 °C.

(4) Minimum value for linear and exponential waveshape to 80% rated V<sub>DRM</sub>. Gate open. T<sub>j</sub> = 125 °C.

(5) Non-repetitive value.

(6) The value of di/dt is established in accordance with EIA/NIMA Standard RS-397, Section 5-2-2-6. The value defined would be in addition to that obtained from a snubber circuit, comprising a 0.2 μF capacitor and 20 ohms resistance in parallel with the thristor under test.

### Conducting - on state

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Average value of on-state current	I <sub>T(AV)</sub>		2619		A	Sinewave, 180° conduction, T <sub>sink</sub> =55°C
RMS value of on-state current	I <sub>TRMS</sub>		3300		A	Nominal value
Peak one cPSTCle surge (non repetitive) current	I <sub>TSM</sub>		38000 36000		A A	8.3 msec (60Hz), sinusoidal wave- shape, 180° conduction, T <sub>j</sub> = 125 °C 10.0 msec (50Hz), sinusoidal wave- shape, 180° conduction, T <sub>j</sub> = 125 °C
I square t	I <sup>2</sup> t		5.5x10 <sup>6</sup>		A <sup>2</sup> s	10 msec
Latching current	I <sub>L</sub>		1000		mA	V <sub>D</sub> = 24 V; R <sub>L</sub> = 12 ohms
Holding current	I <sub>H</sub>		500		mA	V <sub>D</sub> = 24 V; I = 2.5 A
Peak on-state voltage	V <sub>TM</sub>		2.0		V	I <sub>TM</sub> = 4000 A; T <sub>j</sub> = 125 °C
Critical rate of rise of on-state current (5, 6)	di/dt		800		A/μs	Switching from V <sub>DRM</sub> ≤ 1000 V, non-repetitive
Critical rate of rise of on-state current (6)	di/dt		300		A/μs	Switching from V <sub>DRM</sub> ≤ 1000 V

**Gating**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Peak gate power dissipation	P <sub>GM</sub>		200		W	t <sub>p</sub> = 40 us
Average gate power dissipation	P <sub>G(AV)</sub>		5		W	
Peak gate current	I <sub>GM</sub>		20		A	
Gate current required to trigger all units	I <sub>GT</sub>		300 200 125		mA	V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = -40 °C V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = +25 °C V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = +125 °C
Gate voltage required to trigger all units	V <sub>GT</sub>	0.30	5 4		V	V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = -40 °C V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = 0-125 °C V <sub>D</sub> = Rated V <sub>DRM</sub> ; R <sub>L</sub> = 1000 ohms; T <sub>j</sub> = + 125 °C
Peak negative voltage	V <sub>GRM</sub>		20		V	

**Dynamic**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Delay time	t <sub>d</sub>		2.0		μs	I <sub>TM</sub> = 50 A; V <sub>D</sub> = 67% V <sub>DRM</sub> Gate pulse: V <sub>G</sub> = 30 V; R <sub>G</sub> = 10 ohms; t <sub>r</sub> = 0.1 μs; t <sub>p</sub> = 20 μs
Turn-off time (with V <sub>R</sub> = -5 V)	t <sub>q</sub>		60	50	μs	I <sub>TM</sub> = 4000 A; di/dt = 60 A/μs; V <sub>R</sub> ≥ 50 V; Re-applied dV/dt = 200 V/μs linear to 33% V <sub>DRM</sub> ; T <sub>j</sub> = 125 °C; Duty cPSTCle ≥ 0.01%
Reverse recovery current	I <sub>rr</sub>				A	I <sub>TM</sub> = 4000 A; di/dt = 60 A/μs; V <sub>R</sub> ≥ -50 V; T <sub>j</sub> = 125 °C

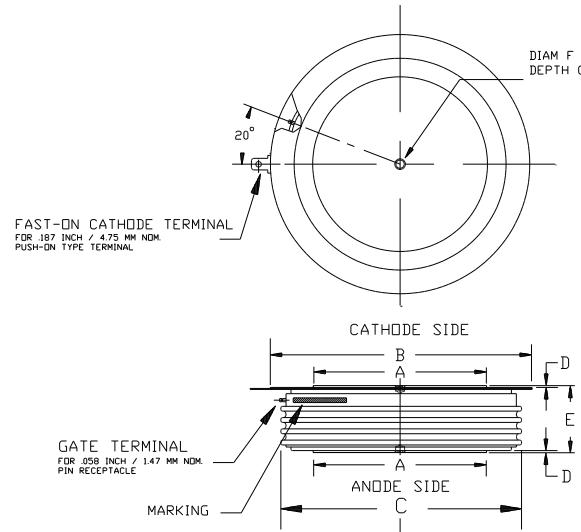
**THERMAL AND MECHANICAL CHARACTERISTICS AND RATINGS**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Operating temperature	T <sub>j</sub>	-40	+125		°C	
Storage temperature	T <sub>stg</sub>	-40	+150		°C	
Thermal resistance - junction to case	R <sub>θ(j-c)</sub>		0.012		°C/W	Double sided cooled Single sided cooled
Thermal resistamce - case to sink	R <sub>θ(c-s)</sub>		0.002		°C/W	Double sided cooled * Single sided cooled *
Mounting force	P	8000 35.5	10000 44.4		lb. kN	
Weight	W			3.5 1.60	lb. Kg.	

\* Mounting surfaces smooth, flat and greased

Note : for case outline and dimensions, see case outline drawing in page 3 of this Technical Data

**Technical Data :**



**CASE 5T**  
**NOMINAL OUTLINE DIMENSIONS**

DIMENSIONS	INCH	MM
DIAM. A	2.88	73.2
DIAM. B	4.36	110.7
DIAM. C	3.95	100.3
D	.030	.76
E	1.400 / 1.440	35.56 / 36.58
F	.140	3.56
G	.080	2.03

STRIKE DISTANCE = 1.04 inch / 26.4 mm MIN.  
CREEPAGE DISTANCE = 1.64 inch / 41.6 mm MIN.